



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C220JB61PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22pF, 50V, ±5%, C0G, 0805

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>220</u> <u>J</u> <u>B</u> <u>6</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor				
2	Size	0805 (inch code)	L: $2.0 \pm 0.1 \text{ m}$	nm W:	1.25 ± 0.1	mm
3	Dielectric	C0G	8 Inner e	lectrode Ni		
4	Capacitance	22 pF	Termin	ation Cu	J	
(5)	Capacitance	±5 %	Plating	Sr	100%	(Pb Free)
	tolerance		9 Produc	t Au	ıtomotive	
6	Rated Voltage	50 V	10 Grade	code St	andard	
7	Thickness	0.6 ± 0.1 mm	① Packag	jing Ca	ardboard Typ	e, 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition		
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C		
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion		
	within ±2.5% or ±0.25pF whichever is larger			
	Q: 840 min			
	IR : More than 10,000№ or 500№×μF			
	Whichever is Smaller			
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles		
	Capacitance Change :	Measurement at 24±2hrs after test conclusion		
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :		
	Q: 840 min	-55+0/-3 °C (15±3min) -> Room Temp(1min.)		
	IR : More than 10,000№ or 500№×μF	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)		
	Whichever is Smaller			
Destructive Physical	No Defects or abnormalities	Per EIA 469		
Analysis				
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle		
	Capacitance Change :	Heat (25~65 °C) and humidity (80~98%), Unpowered		
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion		
	Q: 330 min			
	IR : More than 10,000№ or 500№×μF			
	Whichever is Smaller			
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V,		
	Capacitance Change :	Add 100kohm resistor		
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion		
	Q: 173.33 min	The charge/discharge current is less than 50mA.		
	IR : More than 500 MΩ or 25 MΩ×μF			
	Whichever is Smaller			
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125 ℃, 200% Rated Voltage,		
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion		
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.		
	Q: 330 min			
	IR : More than 10,000№ or 500№×μF			
	Whichever is Smaller			

	Performance	Test condition		
External Visual	No abnormal exterior appearance	Microscope ('10)		
Physical Dimensions	Within the specified dimensions	Using The calipers		
Mechanical Shock	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) Peakvalue Duration Wave Velocity 1,500G 0.5ms Half sine 4.7m/sec.		
Vibration	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"x5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000 Hz.		
Resistance to Solder Heat	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	Solder pot : 260±5°C, 10±1sec.		
Thermal Shock	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	-55°C/+125°C. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air		
ESD	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	AEC-Q200-002		
Solderability	95% of the terminations is to be soldered evenly and continuously	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C solder: a solution ethanol and rosin		
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 ℃,		
Characterization	Q: 840 max. IR(25℃): More than 100,000MΩ or 1,000MΩ×μF IR(125℃): More than10,000MΩ or 100MΩ×μF Whichever is Smaller Dielectric Strength	1Mb±10%, 0.5~5Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25℃, @125℃ for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds		
Board Flex	Appearance: No abnormal exterior appearance Capacitance Change: within ±5.0% or ±0.5pF whichever is larger	Bending to the limit (3mm) for 5 seconds		
Terminal Strength(SMD)	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger	18N, for 60±1 sec.		
Beam Load	Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N	Beam speed 0.5±0.05mm/sec		
Temperature Characterisitcs	C0G (From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/ ℃)			

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\!\!\mathrm{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.